

L Number	Hits	Search Text	DB	Time stamp
1	54309	(Chemical adj mechanical adj polish\$3) or CMP or planariz\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:14
36	54		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:29
43	721	((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:27
50	316	(((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:27
57	42	((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)) and (thickness with variation\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:28
64	54	((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)) and (device near3 region\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:29
71	91	((((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)) and (thickness with variation\$1)) or ((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)) and (device near3 region\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:29
85	7	((((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)) and (thickness with variation\$1)) or ((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)) and (device near3 region\$1))) and (test\$3 with region\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:45
92	84	((((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)) and (thickness with variation\$1)) or ((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)) and (device near3 region\$1))) not (((((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)) and (thickness with variation\$1)) or ((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (pattern near3 density)) and (etch\$3 with pattern)) and (device near3 region\$1))) and (test\$3 with region\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/20 10:46